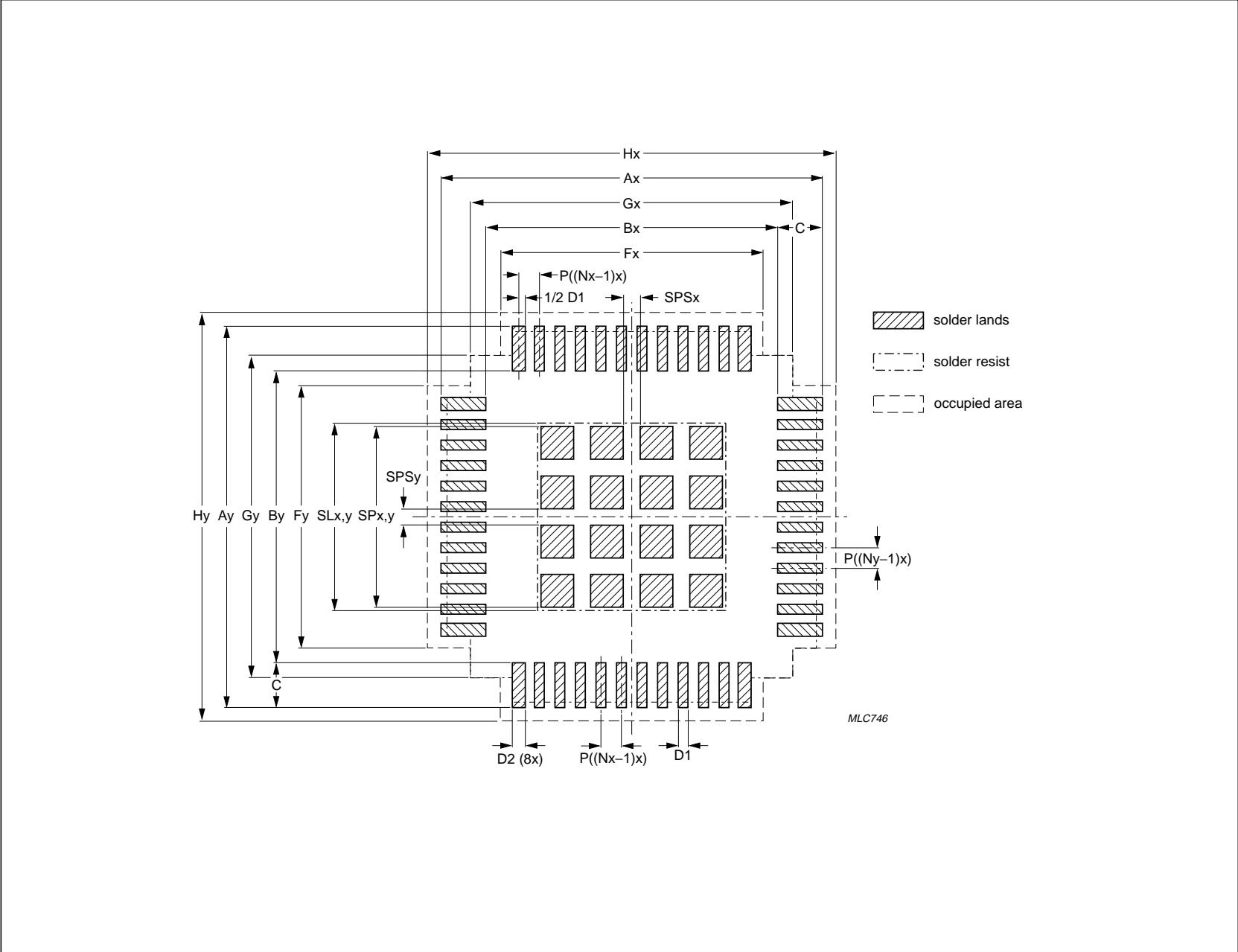


HTQFP, HLQFP, LQFP FOOTPRINT (REFLOW SOLDERING)



Reflow soldering

PACKAGE NAME	PHILIPS OUTLINE CODE	Nx	Ny	FOOTPRINT DIMENSIONS (mm)														PLACEMENT ACCURACY
				P	Ax	Ay	Bx	By	C	D1	D2	Fx	Fy	Gx	Gy	Hx	Hy	
HTQFP32 ⁽¹⁾	SOT-547-1	8	8	0.50	7.40	7.40	5.50	5.50	0.95	0.25	0.30	4.45	4.45	5.90	5.90	8.00	8.00	±0.10
HTQFP32 ⁽¹⁾	SOT547-2	8	8	0.50	7.40	7.40	5.30	5.30	1.05	0.28	0.40	4.65	4.65	5.90	5.90	8.00	8.00	±0.10
HTQFP48 ⁽¹⁾	SOT545-2	12	12	0.50	9.50	9.50	7.30	7.30	1.10	0.25	0.30	7.20	7.20	7.20	7.20	10.75	10.75	±0.10
HTQFP80 ⁽¹⁾	SOT513-1	20	20	0.65	16.35	16.35	14.15	14.15	1.10	0.40	0.40	13.11	13.11	14.25	14.25	16.60	16.60	±0.10
HLQFP100 ⁽¹⁾	SOT470-1	25	25	0.50	16.50	16.50	14.20	14.20	1.15	0.30	0.40	12.75	12.75	14.90	14.90	16.75	16.75	±0.10
LQFP32	SOT358-1	8	8	0.80	9.50	9.50	7.30	7.30	1.10	0.40	0.40	6.40	6.40	7.25	7.25	9.75	9.75	±0.15
LQFP32	SOT401-1	8	8	0.50	7.40	7.40	5.20	5.20	1.10	0.30	0.40	4.25	4.25	5.90	5.90	7.65	7.65	±0.15
LQFP44	SOT389-1	11	11	0.80	12.35	12.35	10.35	10.35	1.00	0.40	0.40	8.80	8.80	10.25	10.25	12.60	12.60	±0.15
LQFP48	SOT313-2	12	12	0.50	9.50	9.50	7.30	7.30	1.10	0.285	0.285	7.20	7.20	7.20	7.20	10.75	10.75	±0.10
LQFP64	SOT314-2	16	16	0.50	12.50	12.50	10.30	10.30	1.10	0.285	0.285	9.035	9.035	10.20	10.20	13.75	13.75	±0.10
LQFP64	SOT414-1	16	16	0.40	9.40	9.40	7.20	7.20	1.10	0.23	0.30	6.62	6.62	6.90	6.90	9.65	9.65	±0.10
LQFP80	SOT315-1	20	20	0.50	14.50	14.50	12.30	12.30	1.10	0.285	0.285	11.04	11.035	12.20	12.20	15.75	15.75	±0.10
LQFP100	SOT407-1	25	25	0.50	16.50	16.50	14.20	14.20	1.15	0.300	0.40	12.75	12.75	14.90	14.90	16.75	16.75	±0.10
LQFP128	SOT420-1	32	32	0.40	16.40	16.40	14.20	14.20	1.10	0.23	0.30	13.02	13.02	14.90	14.90	16.65	16.65	±0.10
LQFP128	SOT425-1	38	26	0.50	22.50	16.50	20.30	14.30	1.10	0.285	0.285	20.04	14.035	20.20	14.20	23.75	17.75	±0.10
LQFP144	SOT486-1	36	36	0.50	22.35	22.35	20.15	20.15	1.10	0.285	0.285	18.11	18.11	20.20	20.20	22.60	22.60	±0.10
LQFP160	SOT435-1	40	40	0.50	26.35	26.35	24.15	24.15	1.10	0.285	0.285	20.11	20.11	24.20	24.20	26.60	26.60	±0.10
LQFP176	SOT506-1	44	44	0.50	26.35	26.35	24.15	24.15	1.10	0.285	0.285	20.11	20.11	24.20	24.20	26.60	26.60	±0.10

Note

1. These packages have a heatsink soldered to the board. The dimensions of these solder lands are given in the following table.

PACKAGE NAME	PHILIPS OUTLINE CODE	SOLDER LAND DIMENSIONS (mm)					
		SLx	SLy	SPx	SPy	SPSx	SPSy
HTQFP32	SOT-547-1	3.60	3.60	3.50	3.50	0.55	0.55
HTQFP32	SOT547-2	3.20	3.20	3.10	3.10	0.50	0.50
HTQFP48	SOT545-2	4.70	4.70	4.60	4.60	0.40	0.40
HTQFP80	SOT513-1	5.30	6.00	5.20	5.90	0.20	0.25